MPI TS3000-DS | 300 mm Automated Probe System

The Dedicated Double-Sided Test System for PIC-EIC Testing, e.g. COUPE™* Characterization

Microscope and Optics Options

- Stable microscope bridge mount with 50 x 50 x 140 mm programmable movement
- Various optics options available such as MPI AMZ12 with up to 12x optical zoom or MPI iMAG® - the digital microscope
- Probe-To-Pad-Alignment (PTPA) for vertical probe cards

Optical Setup

- Hexapod-NanoPositioner combination
- Surface and edge coupling devices
- East, west or east-west configuration
- On top or bottom side of the wafer

Electrical Setup

- Probe card in 4.5 inch width format
- DC and RF MicroPositioners
- On top side of the wafer
- Optional high-pin count support, up to 35 kg force

MicroPositioners

- Supports up to 4 RF and 10 DC MicroPositioner
- Wide range of MicroPositioners available
- Dedicated Coax, Triax and Kelvin probe arms

Top Probe Platen

- Stable and rigid design
- Rectangular adjustments for RF positioners
- Integrated air-cooling for maximum thermal stability

Bottom Probe Platen

- For Hexapod-NanoPositioner combination
- Integrated z-travel for contact-separation movement

Integrated Vibration Isolation Table

- Incorporates a high performance vibration isolation platform
- Optimal working height for ergonomic daily operation

Software Suite SENTIO® (Windows 11)

- Simple and intuitive operation by revolutionary, multi-touch software control saves significant training time
- Scroll, Zoom, Move commands mimic modern smart mobile devices and allows to become an expert in just minutes
- Switching between the active application and the rest of the APPs is just matter of a simple finger sweep
- MPI RF calibration software program QAlibria® is fully integrated with SENTIO® – for ease of use by following a single operational concept methodology
- GPIB, TCP/IP interface for remote control
- Fully integrated SiPH functionality for double-sided testing

SiPH Calibration Areas

- Two calibration areas on the top and bottom side
- Adjustment of the fiber height and rotation angles
- Unique calibration at the set chuck temperature
- For maximum alignment accuracy

Integrated Hardware Control Panel

- Provide faster, safer and convenient system control and test operation
- Keyboard and mouse are strategically located to control the software or the measurement instruments

GridChuck™

- For 300 mm wafer, wafer shards and singulated dies
- Designed for electrical contact on the top and optical access from the bottom side
- Customized backside opening according to wafer layout
- Insulated banana chuck connection

Thermal Chuck Integration

- Thermal GridChuck™ can be operated by using the fully integrated touchscreen display
- Convenient location in front of the operator for fast operation and immediate feedback
- Temperature capability from room temperature to 150°C

**COUPE™ is a trademark of Taiwan Semiconductor Manufacturing Company (TSMC).*